



Implementing Security on the Embedded Internet of Things using SE for Android

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Agenda

- Digi Introduction
- Digi Freescale-based Embedded Solutions
- Android Operating System Overview
- Security Enhancements (SE) for Android – Details
- Digi Development Kit Offering

Digi: Strength In Numbers

285

PATENTS ISSUED
AND PENDING

100M

THINGS
CONNECTED

25K

CUSTOMERS

DGII NASDAQ

1985 Year
Founded

600 Employees
Worldwide

12 Consecutive
Years of
Profitability

200 Million In
Revenue

100 Million
In Cash

Extensive Global Reach



HQ Minnetonka, MN, USA

16 Regional Offices

200+ Digi Technical Resources

250+ Channel Partners

800+ Channel Technical Resources

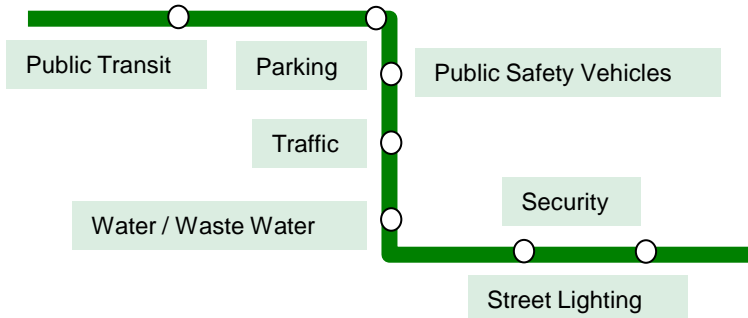
Digi EMEA



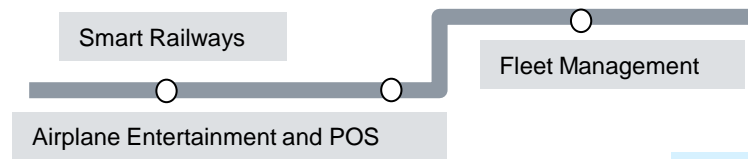
- **HQ in Paris:**
 - European Management
 - Marketing & Sales
- **Sales Offices:**
 - Belgium, Denmark, France, Germany, Russia & Eastern Europe, Spain, The Netherlands, UK
- **Admin & Support Center in Dortmund:**
 - Finance
 - Product Specialists
 - Technical Support
- **R&D locations:**
 - Logroño, Spain
- **Distribution Channel:**
 - Strong network of distribution partner and Integrators

Success Across Six Industries

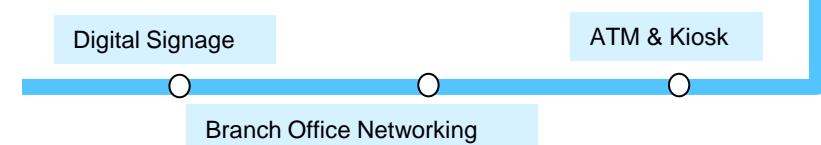
Government



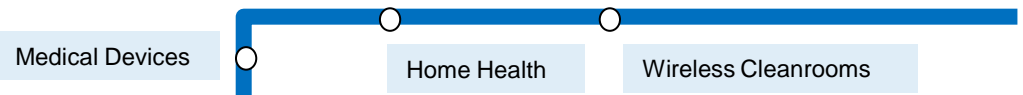
Transportation



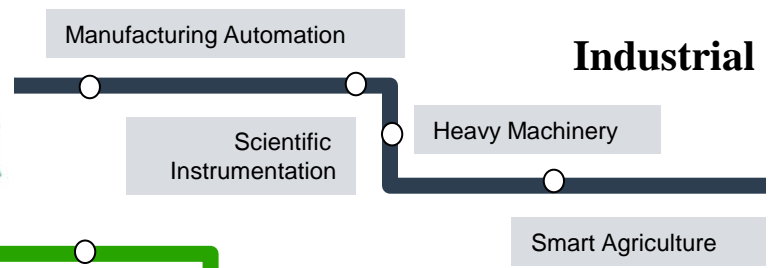
Retail



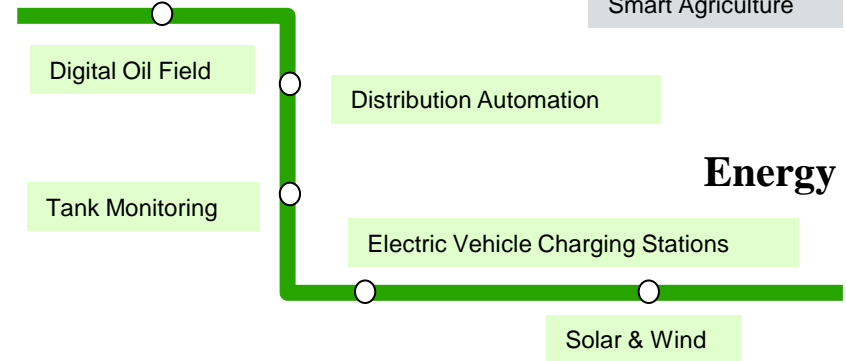
Medical



Industrial



Energy



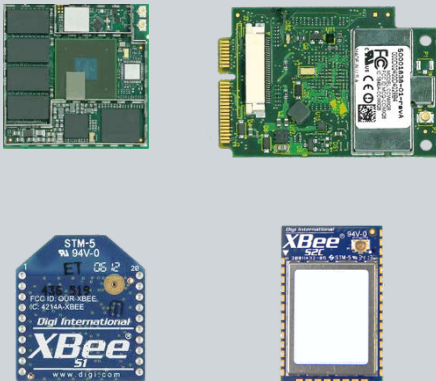
Award-Winning Products & Services

Create

Deploy

Manage

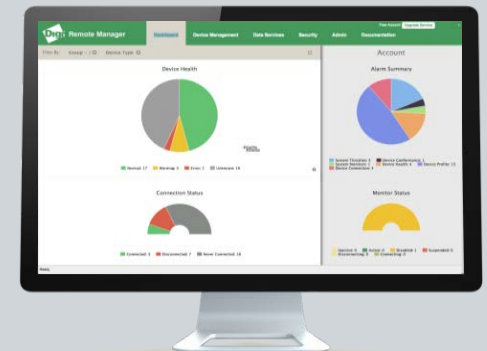
RF Modules
Embedded Modules & SBCs
Wireless Design Services



Wireless Routers and Gateways
Device Networking Solutions



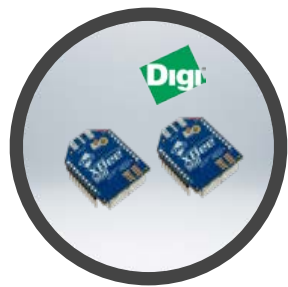
Digi Remote Manager
Digi Device Cloud
Etherios Cloud Services



Complete end-to-end IoT Solution



Equipment



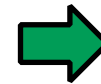
Sensor/Nodes



Aggregator/ Gateway



Infrastructure



Application

ConnectCore for Freescale i.MX



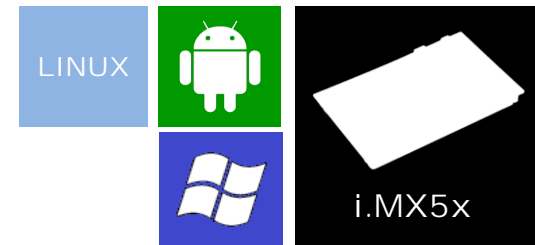
ConnectCard for i.MX28

- Freescale i.MX28
- ARM926EJ-S running at up to 454 MHz (1.2 DMIPS/MHz)
- 802.11a/b/g/n + Bluetooth 4.0, single/dual 10/100 Mbit/s Ethernet
- LCD, UART, USB, CAN, SPI, I2C, I2S, ADC, GPIO
- PCI Express Mini Card form factor (51 mm x 35 mm x 3 mm)
- Up to -40 to 85°C operating temperature



ConnectCore for i.MX53

- Freescale i.MX53
- Cortex-A8 running up to 1 GHz (2.0 DMIPS/MHz)
- 802.11a/b/g/n, single/dual 10/100 Mbit/s Ethernet
- Dual-display, 2D/3D GPU, 720p/1080p VPU, dual camera
- USB, UART, SPI, I2C, I2S, ADC, SD/MMC, CAN, SATA, GPIO
- Compact 82 mm x 50 mm x 8 mm footprint
- Industrial operating temperature -40 to 85°C



ConnectCore 6

- Freescale i.MX6 (Solo/Dual/Quad) Multichip Module
- Cortex-A9 running at up to 1.2 GHz (2.4 DMIPS/MHz)
- 802.11a/b/g/n + Bluetooth 4.0, Gigabit Ethernet
- Kinetis KL2/K20 microcontroller assist option
- Up to 4 displays, 2D/3D GPU, 1080p VPU, dual camera
- CAN, USB, UART, SPI, I2C, I2S, SD/MMC, SATA, PCIe, GPIO
- Low-profile 50 mm x 50 mm x 5 mm footprint (SMT)
- Industrial operating temperature -40 to 85°C



Freescale i.MX6

DIGI CONNECTCORE 6

ConnectCore 6



ConnectCore for i.MX6

- Freescale i.MX6, up to 64 GB eMMC, 2 GB DDR3
- Up to four Cortex-A9 cores up to 1.2 GHz (2.5 DMIPS/MHz)
- On-module Dialog PMIC with high efficiency
- **Ultra low-power Freescale Kinetis KL2 / K20 (Cortex-M0+/M4) micro for unique power management and customer specific implementations**
- **802.11a/b/g/n + Bluetooth 4.0**, single Gigabit Ethernet (MII) w/IEEE1588
- Up to 4 displays, 3D GPU with up to 4 shaders, up to two 2D GPUs, 1080p VPU
- UART, USB, CAN, MIPI DSI/CSI, CSI, I2C, I2S, crypto/security, MMC/SDXC, PCI Express (x1)
- **SMT module, LGA-400, 50 mm x 50 mm max**
- **Industrial operating temperature -40 to 85°C**



• Innovative, cost-efficient and reliable wireless multichip module solution

- LGA module, BGA optional, 50x50 mm, 400 pads, allowing automated placement
- Connector-less mounting for reduced system cost and reliability
- Pre-certified 802.11abgn + Bluetooth 4.0 connectivity options

• Truly scalable embedded platform solution

- Performance scalability through footprint-compatible single, dual, and quad core variants
- Unique design-for-cost scalability extending from low to high volume applications

• Quick time-to-market through embedded services offering

- Design services support for customization, antenna design, cellular integration, regulatory/carrier compliance, etc.



ConnectCore 6

ConnectCore for i.MX6

- Freescale i.MX6, up to 64 GB eMMC, 2 GB DDR3
- Up to four Cortex-A9 cores up to 1.2 GHz (2.5 DMIPS/MHz)
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- **SMT module, LGA-400, 50 mm x 50 mm max**
- **Industrial operating temperature -40 to 85°C**



i.MX 6Solo

- Single ARM Cortex-A9 at 1.0GHz
- **512KB** L2 cache, Neon, VFPv16, Trustzone
- **3D graphics** with 1 shader
- 2D graphics
- 32-bit DDR3 at 400MHz
- Integrated EPD controller

i.MX 6DualLite

- **Dual** ARM Cortex-A9 at 1.0GHz
- 512KB L2 cache, Neon, VFPv16, Trustzone
- 3D graphics with 1 shader
- 2D graphics
- **64-bit** DDR3 at 400MHz
- Integrated EPD controller

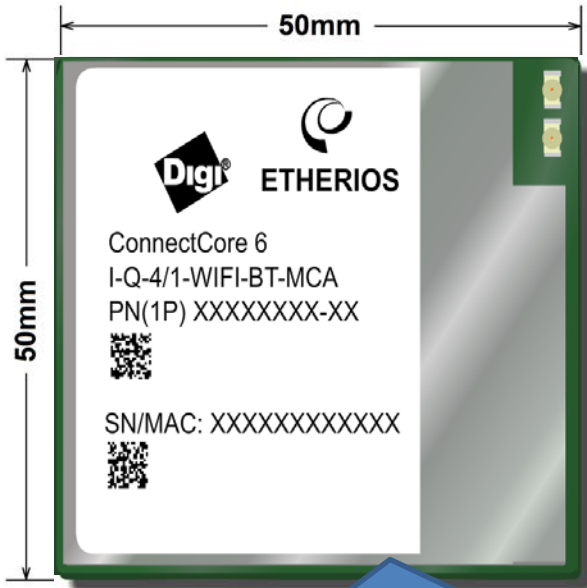
i.MX 6Dual

- **Dual** ARM Cortex-A9 at 1/1.2GHz
- **1 MB** L2 cache, Neon, VFPv16, Trustzone
- 3D graphics with **4 shaders**
- **Two** 2D graphics engines
- 64-bit DDR3 at **533MHz**
- Integrated **SATA-II**

i.MX 6Quad

- **Quad** ARM Cortex-A9 at 1.2GHz
- 1 MB L2 cache, Neon, VFPv16, Trustzone
- 3D graphics with 4 shaders
- **Two** 2D graphics engines
- 64-bit DDR3 at 533MHz
- Integrated SATA-II

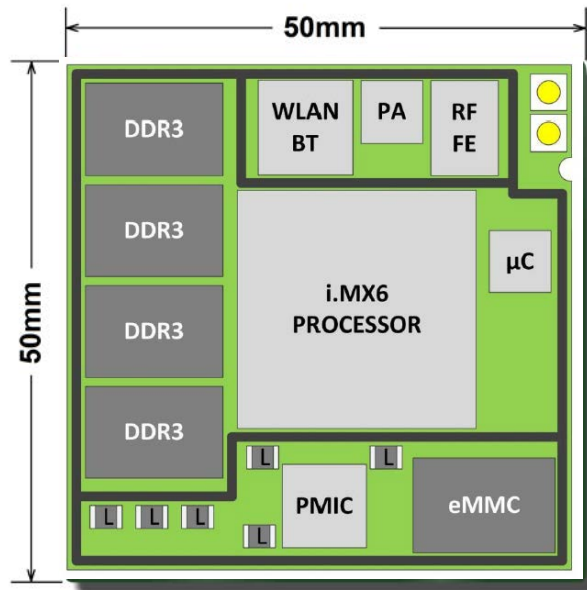
ConnectCore 6: Solution Benefits 1/2



- **Low-profile, ultra-compact form factor**
 - Enabling customers to build compact products, including mobile and semi-mobile applications
- **Common footprint w/scalable performance**
 - Embedded product platform suitable for wide range of applications, both performance and cost
- **Industry's first surface mount (SMT) module**
 - Mounting without connectors for superior reliability, reduced system cost, low profile
- **Completely shielded single component**
 - Low emissions (FCC Class B) and surface for simplified thermal management
- **Integrated Gigabit Ethernet and secure wireless connectivity options**
 - Complete wired and wireless connectivity

- Dramatically reduced design risk, effort, and accelerated Time to Market
- Designed for product reliability and longevity
- Guaranteed long-term availability for embedded designs

ConnectCore 6: Solution Benefits 2/2

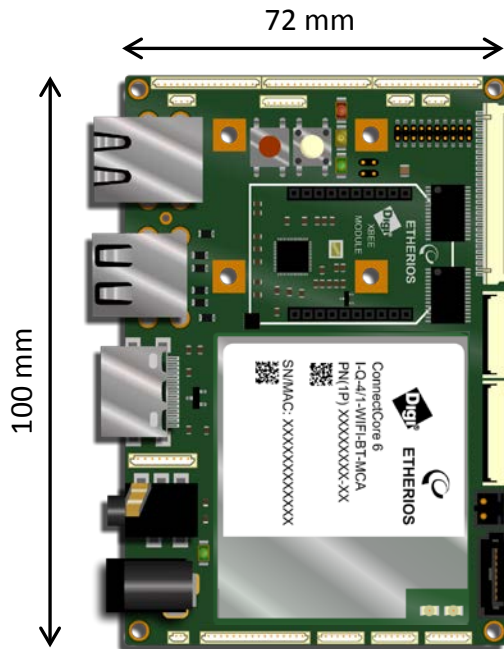


- **Superior Thermal Behavior**
 - Thermally modeled design
 - Internal thermal compound (Tputty) to make conduction path to the shield / heatsink
- **True Industrial Design**
 - Industrial rated SOC used on industrial CC6
 - Enabling 24/7 applications >10 year lifetime!
 - Dialog PMIC for superior power management
 - HALT and Vibration tested






TIM = Thermal Interface Material

ConnectCore 6: SBC Approach

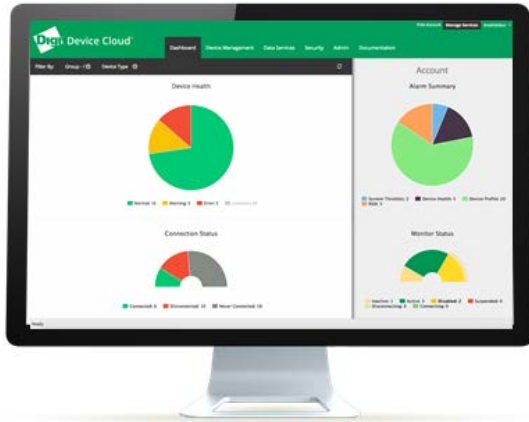


- **Included in ConnectCore 6 dev kits**
 - Carrier board with ConnectCore 6 module
 - Complete design files available (Altium 14) to customers online for reference/customization
- **Also sold to customers as a Digi product**
 - Selected variants will be available
 - Industrial temperature options
 - With product reliability testing
 - Reference enclosure design files posted online
- **Extends reach into new opportunities**
 - Prototyping, proof-of-concept for module
 - New SBC-only opportunities (100 to 1,000 units)
- **Fully connected platform design capabilities**
 - Wi-Fi, Bluetooth, XBee, Cellular, Ethernet

Embedded Operating System Offering

			
Kernel	Linux 3.10	Linux 3.10	Windows Embedded
Positioning	<p>Maximum flexibility – build your own custom Linux distribution</p> <p>QT / GTK support for graphical development</p>	<p>Easy Java application development including graphical user interface programming</p>	<p>Fully componentized and complete offering of high-level Windows components, including GUI , multimedia, and IPv4/v6 networking</p>
Development Tools	<p>Command line / Eclipse plugin C/C++</p>	<p>Digi ESP Java</p>	<p>MS Visual Studio C#,VB,C++</p>

Digi Device Cloud



Enterprise Solution

- Cloud service for Device connectivity, management and integration
- Secure platform for application development
- PCI-DSS validated with “Report on Compliance”

Simplifies Complexities of:

- Taking applications to market
- Integrating new things
- Managing infrastructure
- Managing growth
- Security requirements

Commercial-Grade Reliability:

- Change-Control Management
- Server Management
- Access Management
- Systems & Performance Monitoring
- Logging
- Disaster Recovery

Target Users:

- ✓ Application Developer
- ✓ Solution Provider

- ✓ Value Add Reseller
- ✓ Integrators



Android Adoption

- 1 Billion+ Android device activations since 2008
- Activation rate in July 2013 was 1.5 million/day
- Android becomes increasingly more attractive to embedded developers due to UX integration, Java and a vibrant community



Source: Google, 2014

Consumer Appliance Example



Smart Fridge-freezer

- Samsung RF4289HARS
- WLAN-enabled LCD
- Closed Android system
- Apps included
 - Memos
 - Picasa
 - Epicurious
 - Calendar
 - Weatherbug
 - AP News
 - Pandora
 - Twitter
 - Control Settings

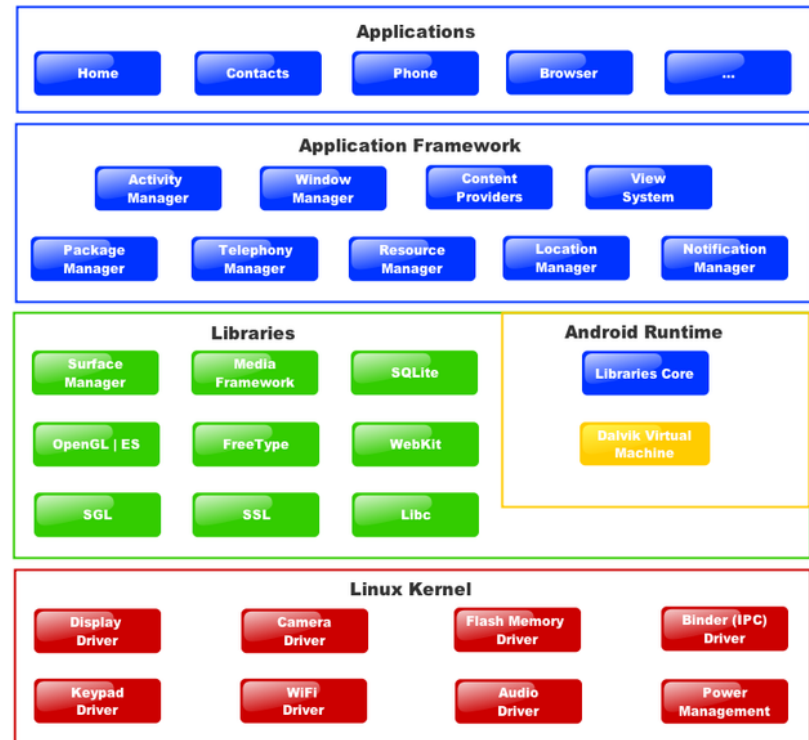
Android Overview

- Complete Software Stack for Mobile Devices
 - Operating system based on Linux kernel
 - Middleware
 - Key Applications
- Royalty free
- Open Source (published by Google)
- Spec defined by Open Handset Alliance
- Goal: Fast & Easy Application Development
 - Applications written in high-level Java
 - Core apps and user apps use same APIs
 - Users can integrate, extend and replace components



Android Details

- Software stack consists of
 - Java applications running on OO application framework
 - Java core libraries / Dalvik or ART JVM / JIT compiling
- Features
 - Open GL ES 2.0
 - SQLite
 - Wi-Fi, Cellular, BT
 - Web Browser
 - Java (and C++) Support
 - (Streaming) Media Support
 - Touch / Camera / GPS / Acceler.
 - Google Play Store for Apps (250k+ apps available)
 - Security Enhancements

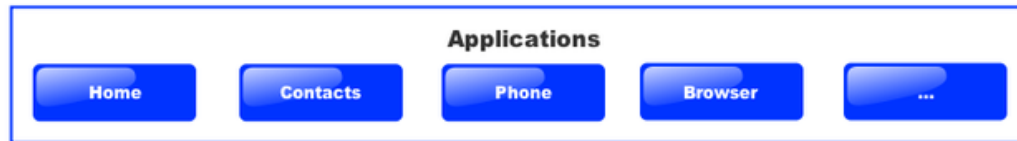


Why Linux as Base System?

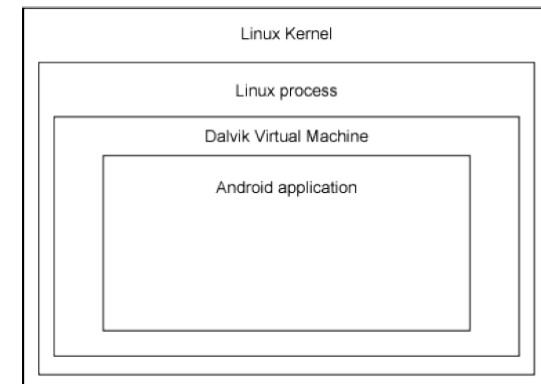
- Open source
- Mature, robust and stable
- Secure
- Android is utilizing
 - Linux Memory and Performance Management
 - Linux Network stack
 - Linux Driver Model
 - Linux Security



Android – Architecture

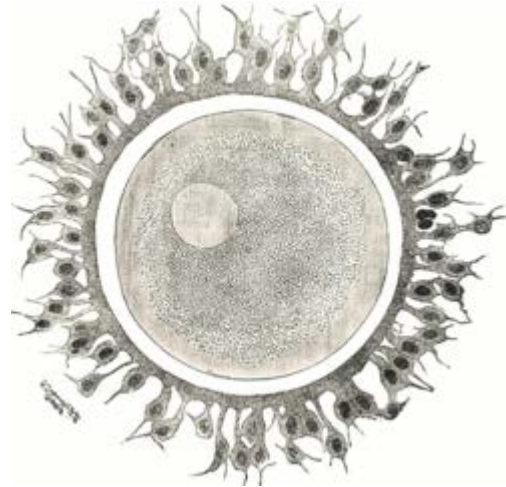


- Each application is started in its own Linux process and as a different Linux user / UID (security)
- Each application runs in its own instance of the Dalvik / ART VM (isolation)
- Each application, by default, has access only to the components that it requires to do its work and no more
- An application can request permission to access device data such as the user's contacts, SMS messages, the mountable storage (SD card), camera, etc.
- All application permissions must be granted by user at install time



Android – Zygote

- Zygote is a special core process started during OS boot process
- As with other Android processes, it runs in it's own instance of the Java VM
- “warmed-up” process that already has core libraries loaded
- Whenever app (new process) is started, it's forked from Zygote
 - There are now 2 VMs (Zygote and the new process)
 - Shared libraries are not copied -> performance gain for starting apps



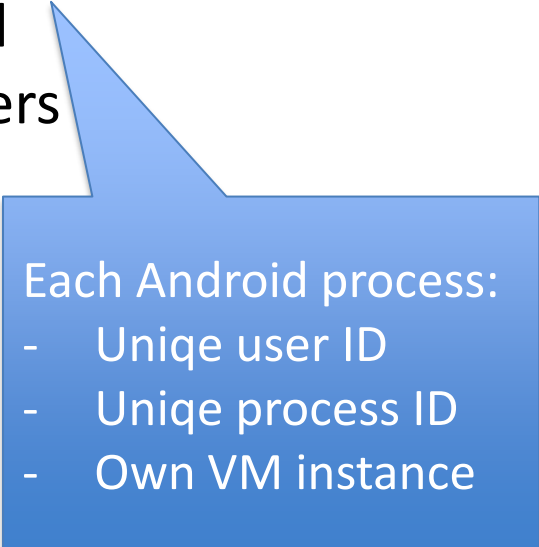
Why Android? - Summary

- Development
 - Fast & easy application development
 - Applications written using high-level Java API
 - Structured code / re-use existing components
 - Outstanding graphical (UI) design & implementation capabilities
- Software
 - Networking , Services & Applications
 - Key applications included
- Support
 - Community and professional
- Free
 - No development or run-time royalties
 - Proprietary Google apps licensing required



Android Security Model prior to SE

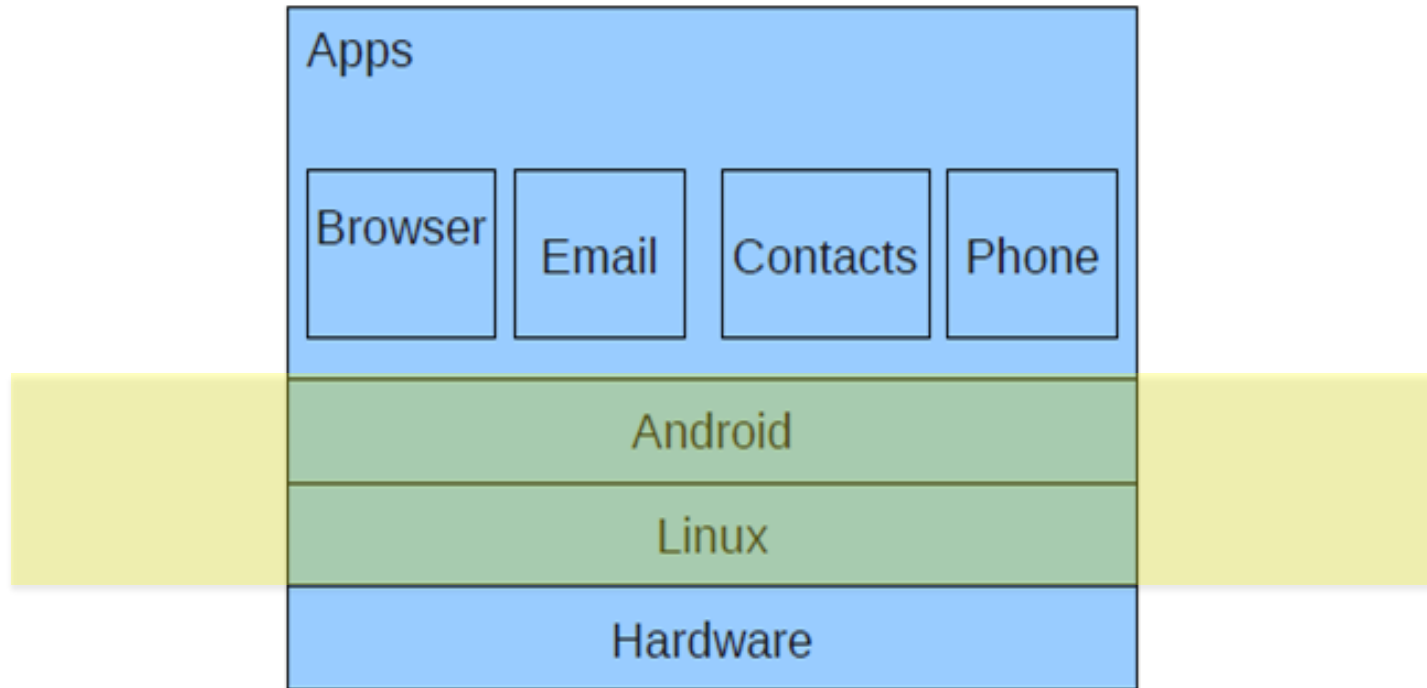
- **Application-level permissions model**
 - Controls access to app components
 - Controls access to system resources
 - Specified by app writers and seen by users (Manifest)
- **Kernel-level sandboxing and isolation**
 - Isolate apps from each other and from system
 - Prevent bypass of app permission model
 - Normally invisible to users and app writers
- **Enforced by Linux kernel**
 - Java VM is not a security boundary
 - Any app can run native code
 - Relies on default Linux security model
 - Discretionary Access Control (DAC)



Each Android process:

- Unique user ID
- Unique process ID
- Own VM instance

Android Security Concerns prior to SE



Example: Skype app

- Weaker separation
- Data / system resource access is entirely at the discretion of the app writer
- Prone to privilege escalation (e.g. root exploits)
- No organizational security goal enforcement

Example: vold daemon

Security Enhancements (SE) for Android

Overview

- **Project to identify and address critical security gaps in Android**
 - Open source project with integration into AOSP
 - Mainline adoption started in Android 4.1 (Jelly Bean)
 - Formerly known as “Security Enhanced Android”
 - Now “Security Enhancements for Android”
- **Scope of project not limited to secure OS aspects**
 - Future efforts may include virtualization and trusted computing
- **Derived from SE Linux**
 - Creators of SE Linux, Xen Security Modules, Linux Kernel Integrity Monitor
 - Driven by NSA’s Trusted Systems Research Group
 - Conducts and sponsors research to provide information assurance for security systems



SE for Android Benefits

- Policy driven access control
- Prevent privilege escalation by apps
- Prevent data leakage by apps
- Prevent bypass of security features
- Enforce legal restrictions on data
- Protect integrity of apps and data



DAC vs. MAC

■ Discretionary Access Control (DAC)

- Access control in Linux prior SE
- Owner of the object specifies which subjects can access object
- Model is called discretionary because of the discretion of owner
- For example, user:group rwx

If also level (sensitivity) and category are specified in a security label, this is called Multi Level Security (MLS)

■ Mandatory Access Control (MAC)

- System policy specifies which subjects can access specific objects
- Uses security labels (metadata) attached to objects and subjects
- For example, user:role:type[:level[:category]]
- When subject (process) attempts to access object (file), the system (kernel) checks whether the policy allows the subject's context to access the object (Type Enforcement)

SE for Android Details



- **Mandatory Access Control (MAC)**
 - Enforces a system-wide security policy
 - Over all processes, objects and operations
 - Based on security labels
- **Can confine flawed and malicious applications**
 - Even ones that run as root
- **Sandbox and isolate apps**
 - Stronger separation
 - Prevent privilege escalation by apps
- **Provide centralized, analyzable policy**
 - Small, fixed policy
 - No policy writing for app developers

Each app has its own
MLS category

A unique domain is
used for every
privileged service

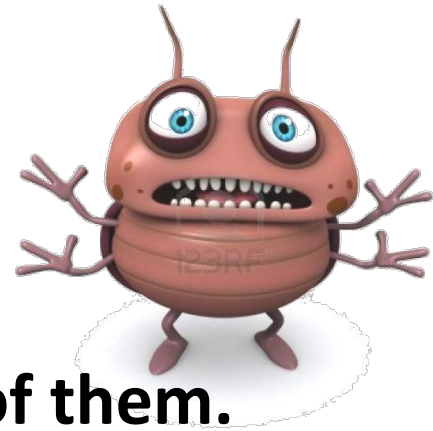
Effectiveness

Root Exploits

- Motochopper
- MempoDroid
- GingerBreak
- Exploid
- Zimperlich
- RageAgainstTheCage
- KillingInTheNameOf

Vulnerable Apps

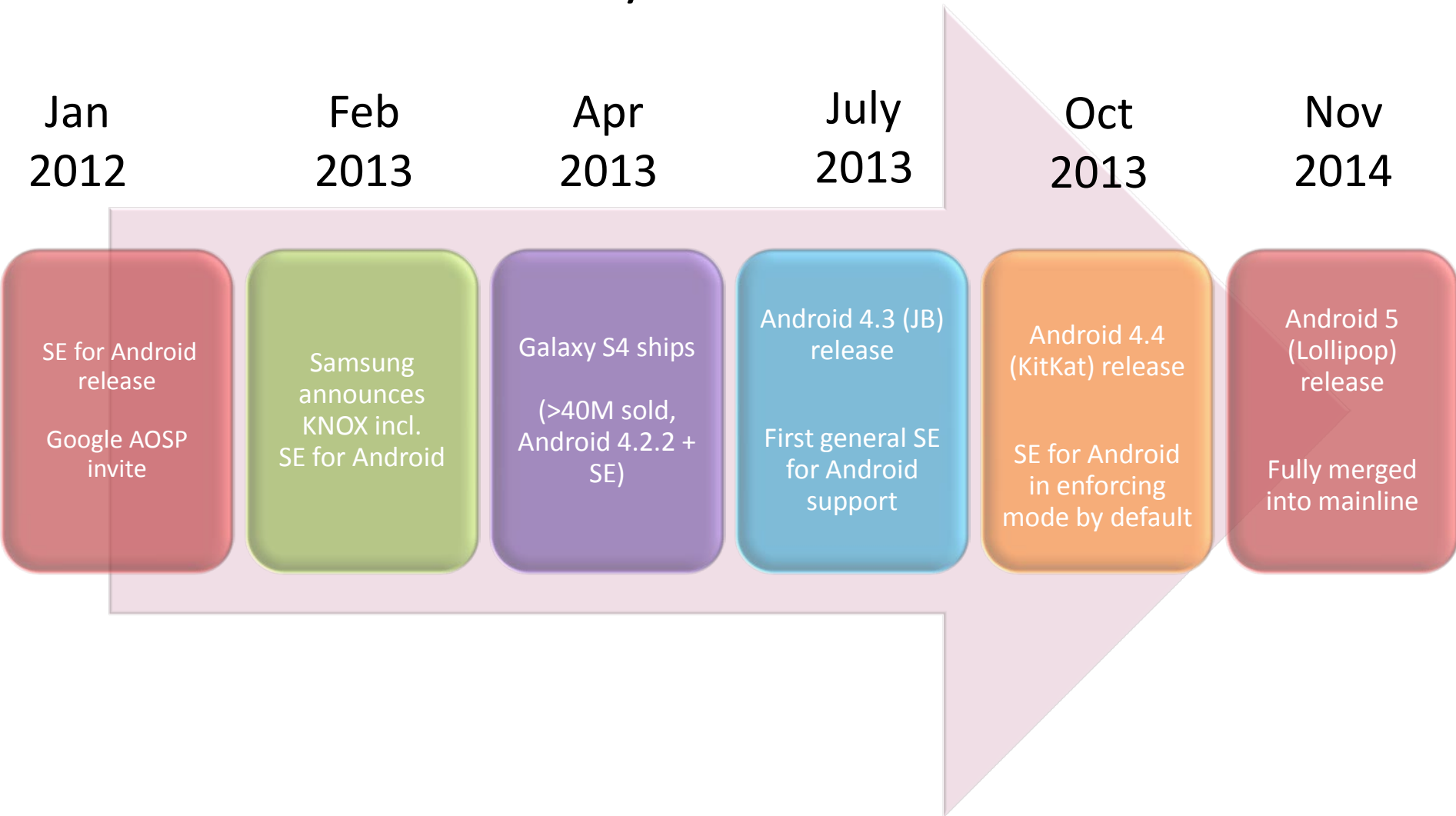
- Skype
- Lookout Mobile
- Security
- Opera Mobile



SE for Android mitigates ALL of them.

SE for Android

Key Milestones

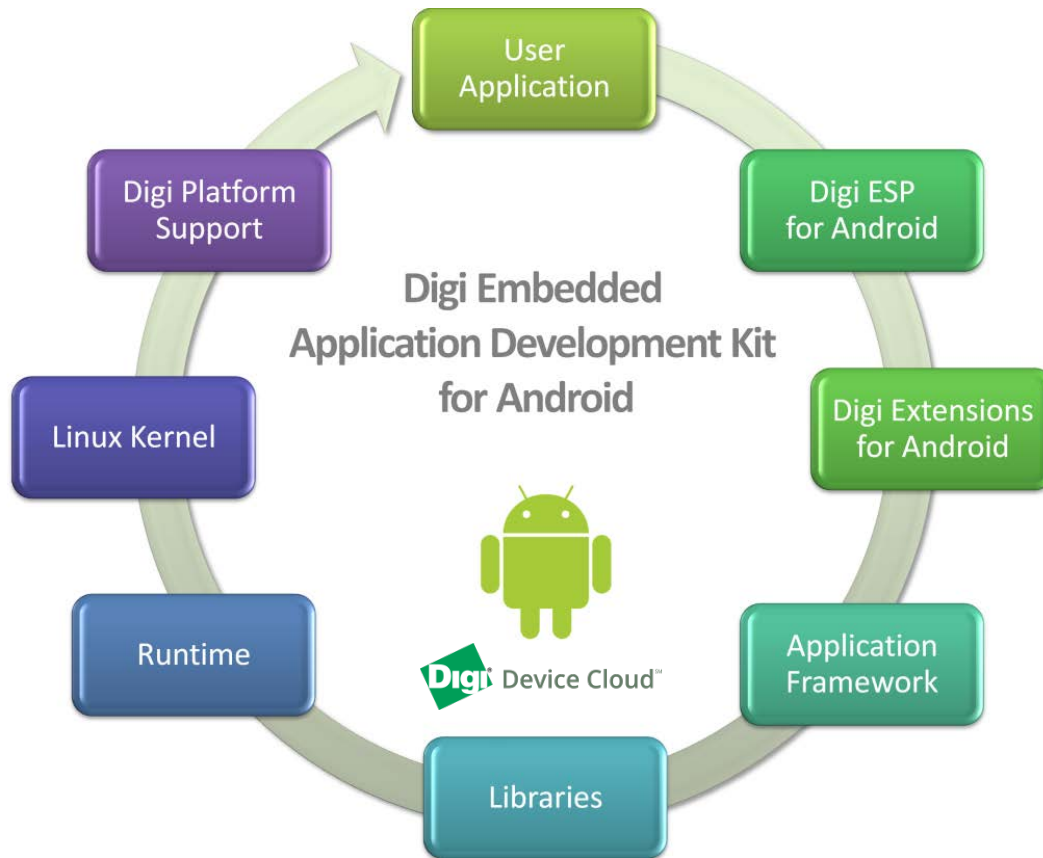


SE for Android

Summary

- **Enabling SE Android in enforced mode will significantly improve operational security of your embedded Android device**
 - Proven immunity from common exploits
 - Separation / sandboxing of apps and related data
- **Impact on memory footprint and performance negligible**
 - Kernel footprint increase ~100-150k
- **Policy changes / customization with granularity**
 - Proceed with care and test!
 - Default system policies are provided (across AOSP)
- **Implemented and enabled today**
 - Android 4.2+ , Samsung Knox, Android for Work
- **Project expected to grow beyond current SE for Android**
 - Virtualization, TrustZone, ...

Digi Development Kit for Android



Digi Development Kit for Android

Features

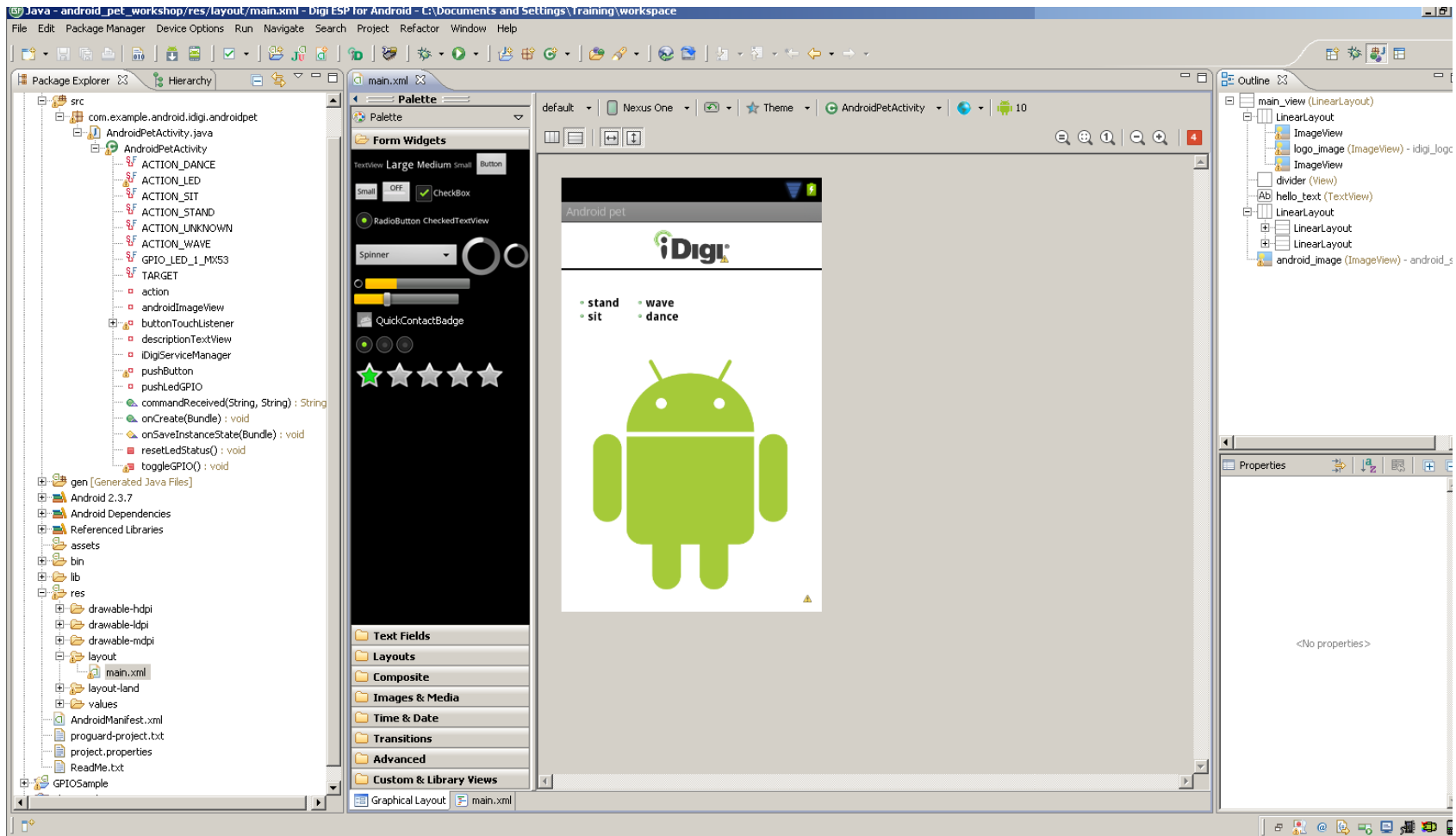
- Ready to use Embedded Android development solution
- Embedded interfaces not common to handsets supported in API
 - e.g. Ethernet, CAN, UART, I2C, SPI, GPIO, ADC, ...
- Support for headless operation
- Highly accelerated and efficient application development
 - Graphical UI builder to modify Android user interface
- No or minimal low-level system development effort
- Digi Device Cloud connector



Digi ESP Development Environment

- Based on Eclipse IDE and Android Development Tools (ADT)
- Providing complete tools to build Android applications
 - Project wizards (sample programs)
 - Workbench / Project Explorer
 - Graphical UI builder (Drag & drop, GUI layout XML code generation)
 - Build and powerful debugging tools
 - Terminal view (serial port monitoring)
 - File Explorer
 - LogCat (monitoring debug output from specific Android processes)
 - Android device view (remote device and task manager)
- Package Manager
- Quick Start Guides, Documentation and Help

Digi ESP for Android Development Environment



Digi Presence at Conference

- Table-top exhibition
- Digi ConnectCore 6 SBC Dual-HDMI Android Demo



Thank You

